\[ \text{diffusion} \to \text{evaporation} \to \text{water} \]

- Aluminum:
  - Rod
- Hot vapor
- Water
- Eupenizers:
  - Spots
- Spots
- Spots
- Spots

- Aluminium chips
- Transmission
- Aluminium chips
- Aluminium chips
- Aluminium chips
- Aluminium chips

- U-float
- Flow grid
- B-569
- O

- E-Zoor for high-level reactor (U.S. DOE)
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and 1,000, can probably work.

$Q = \frac{\text{# molecules/sec}}{V}$

$P = \text{sucrose density of solution}$

$\text{mol/cm}^3 = \frac{\text{g/mol}}{M}$

$Q \text{ flux} = \phi = \text{molecules/sec}$

Susan: dry drop

How fast does $A$ or $H_2O$ diffuse?

association on surface = Heaters

$O_2$ is primary culprit

mmol per day $> 1000$ mg per day

for good film, need the right of $50 \text{ min}$ 1 Torr (best reported)

$= 68 \text{ mm} 1 \text{ Torr}$
for these, use lteffe (Ar)
remove tooth to gel in glass (Cu)

for these, use lteffe (Ar)
Some make not flush to etch (Ag)

Dramatic

polish


each desired etch

deposit direction


dramatic


each desired

deposit direction


dramatic

Tail caper

pr

even

spin, expose, develop pr

strain PR + sonicate (ultrasonic bath)

sidewall striations